

#### 20V N-CHANNEL ENHANCEMENT MODE MOSFET

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> T <sub>A</sub> = +25℃
20V	$11m\Omega$ @ $V_{GS} = 4.5V$	10.5A
	$13m\Omega @ V_{GS} = 2.5V$	9.4A
	$30m\Omega @ V_{GS} = 1.8V$	6.5A
	$50m\Omega$ @ $V_{GS} = 1.5V$	5.5A

#### **Description**

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) and yet maintain superior switching performance, making it ideal for high-efficiency, power-management applications.

#### **Applications**

- General Purpose Interfacing Switch
- Power Management Functions

**Features** 

Additional Tin-Plated on Sidewall Pads for Optical Solder

0.6mm Profile - Ideal for Low Profile Applications

- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Case: U-DFN2020-6/SWP

**Mechanical Data** 

Low Gate Threshold Voltage **ESD Protected Gate** 

- - UL Flammability Classification Rating 94V-0
  - Moisture Sensitivity: Level 1 per J-STD-020
  - Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208@3

Case Material: Molded Plastic, "Green" Molding Compound.

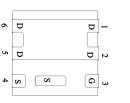
Weight: 0.0065 grams (Approximate)

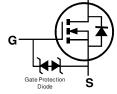




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**Bottom View** 





Pin Out

**Equivalent Circuit** 

#### Ordering Information (Notes 4 & 5)

Part Number	Compliance	Case	Quantity per reel
DMW2013UFDEQ-7	Automotive	U-DFN2020-6/SWP	3,000
DMW2013UFDEQ-13	Automotive	U-DFN2020-6/SWP	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product\_grade\_definitions/.
- 5. For packaging details, go to our website at http"//www.diodes.com/products/packages.html.

# **Marking Information**

U-DFN2020-6/SWP





N6P / N7P = Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013)M = Month (ex: 9 = September)

Date Code Key

Year		2013	3	2014		2015	20	16	2017		2018	2	2019
Code	)	Α		В		С		)	E		F		G
Mont	h	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	)	1	2	3	4	5	6	7	8	9	0	N	D



#### **Maximum Ratings** (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

Characteristic	Symbol	Value	Units			
Drain-Source Voltage	V <sub>DSS</sub>	20	V			
Gate-Source Voltage	V <sub>GSS</sub>	±8	V			
Continuous Durin Comment (Note CVV 4 5V	Steady State	T <sub>A</sub> = +25 °C T <sub>A</sub> = +70 °C	I <sub>D</sub>	10.5 8.5	А	
Continuous Drain Current (Note 6) V <sub>GS</sub> = 4.5V	t < 10s	T <sub>A</sub> = +25 °C T <sub>A</sub> = +70 °C	I <sub>D</sub>	12.5 10.0	А	
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I <sub>DM</sub>	80	Α			
Maximum Body Diode Continuous Current	I <sub>S</sub>	2.5	Α			
Avalanche Current (Notes 7) L = 0.1mH	I <sub>AS</sub>	28	Α			
Single Pulse Avalanche Energy (Notes 8) L = 0.1ml	E <sub>AS</sub>	39.2	mJ			

#### **Thermal Characteristics**

Characteristic		Symbol	Value	Units	
Total Power Dissipation (Note 5)	T <sub>A</sub> = +25℃	D	0.81	W	
Total Power Dissipation (Note 5)	T <sub>A</sub> = +70 ℃	$P_{D}$	0.57		
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	0	185	°C/W	
memial nesistance, Junction to Ambient (Note 5)	t<10s	$R_{\theta JA}$	127	G/VV	
Total Power Dissipation (Note 6)	T <sub>A</sub> = +25 ℃	Б	2.3	W	
Total Fower Dissipation (Note 6)	T <sub>A</sub> = +70 °C	$P_{D}$	1.6		
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	0	65		
Thermal nesistance, Junction to Ambient (Note o)	t<10s	$R_{\theta JA}$	45	°C/W	
Thermal Resistance, Junction to Case (Note 6)		$R_{ heta JC}$	7		
Operating and Storage Temperature Range		$T_{J_1}T_{STG}$	-55 to +175	$^{\circ}$	

# Electrical Characteristics (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	20	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T <sub>J</sub> = +25 °C	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 16V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±5	μΑ	$V_{GS} = \pm 8V$ , $V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	0.5	_	1.1	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$
			8.4	11		$V_{GS} = 4.5V, I_D = 8.5A$
Static Drain-Source On-Resistance	Pag (av)	_	9.8	13	mΩ	$V_{GS} = 2.5V, I_D = 8.5A$
Static Diani-Source On-Nesistance	R <sub>DS</sub> (ON)	_	12	30	11122	$V_{GS} = 1.8V, I_D = 1A$
			15	50		$V_{GS} = 1.5V, I_D = 0.5A$
Diode Forward Voltage	$V_{SD}$	_	_	1.2	V	$V_{GS} = 0V, I_{S} = 8.5A$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C <sub>iss</sub>	_	2,508	_	pF	V 10V V 0V
Output Capacitance	Coss	_	259	-	pF	$V_{DS} = 10V, V_{GS} = 0V,$ - f = 1MHz
Reverse Transfer Capacitance	$C_{rss}$	_	242	l	pF	1 – 1101112
Gate Resistance	$R_g$	_	1.2		Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$
Total Gate Charge (V <sub>GS</sub> = 4.5V)	$Q_{g}$	_	28.7	l	nC	
Total Gate Charge (V <sub>GS</sub> = 8V)	$Q_g$	_	52.6		nC	V 10V I 0.5A
Gate-Source Charge	$Q_{gs}$	_	3.3	_	nC	$V_{DS} = 10V, I_D = 8.5A$
Gate-Drain Charge	$Q_{gd}$	_	5.8	_	nC	
Turn-On Delay Time	t <sub>D(on)</sub>	_	5.8	_	ns	
Turn-On Rise Time	t <sub>r</sub>	_	7.8	_	ns	$V_{DS} = 10V, I_{D} = 8.5A$
Turn-Off Delay Time	t <sub>D(off)</sub>	_	33.3	_	ns	$V_{GS} = 4.5V, R_{G} = 1.8\Omega$
Turn-Off Fall Time	t <sub>f</sub>	_	9.4	_	ns	
Body Diode Reverse Recovery Time	t <sub>rr</sub>	_	11.6	_	ns	$I_F = 8.5A$ , $di/dt = 100A/\mu s$
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	_	4.6	_	nC	I <sub>F</sub> = 8.5A, di/dt = 100A/μs

Notes: 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.

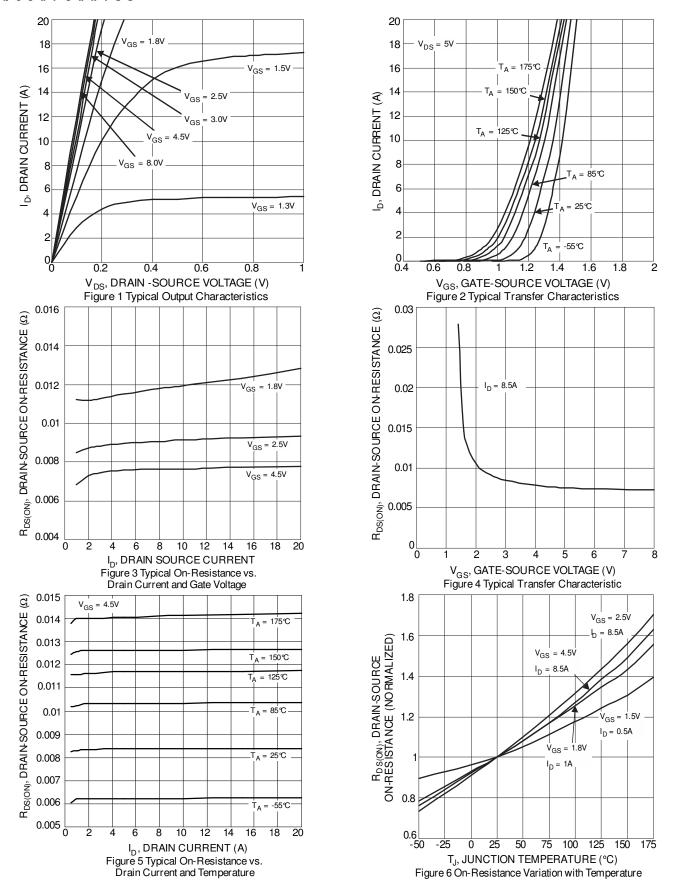
<sup>6.</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1-inch square copper plate.

<sup>7.</sup>  $I_{AS}$  and  $E_{AS}$  rating are based on low frequency and duty cycles to keep  $T_J$  = +25  $^{\circ}$ C.

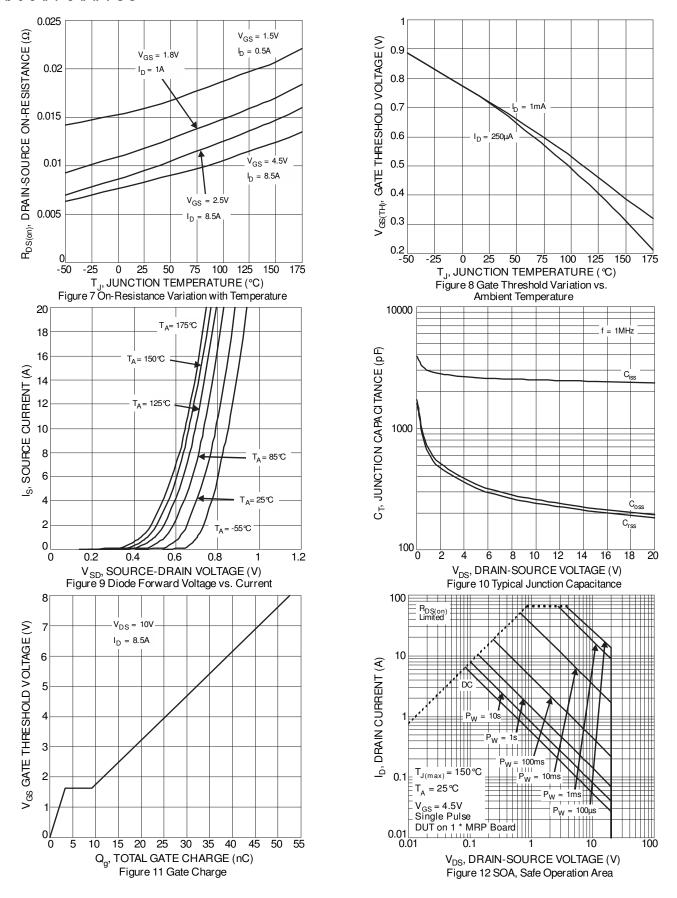
<sup>8.</sup> Short duration pulse test used to minimize self-heating effect.

<sup>9.</sup> Guaranteed by design. Not subject to production testing.

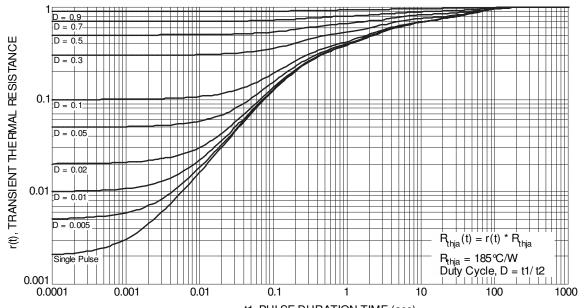










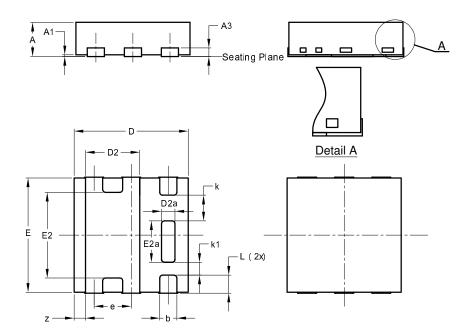


t1, PULSE DURATION TIME (sec) Figure 13 Transient Thermal Resistance



## **Package Outline Dimensions**

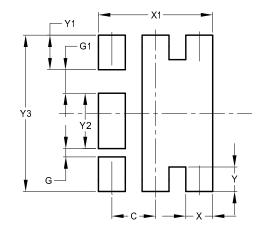
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



U-DFN2020-6/SWP							
Dim	Min	Max	Тур				
Α	0.59	0.65	0.62				
A1	0	0.05	0.03				
А3	1	1	0.19				
b	0.28	0.38	0.33				
D	1.95	2.05	2.00				
D2	0.87	1.07	0.97				
D2a	0.205	0.305	0.255				
Е	1.95	2.05	2.00				
E2	1.42	1.62	1.52				
E2a	0.69	0.79	0.74				
е		0.65 B	SC				
L	0.28 0.38 0.33						
k	0.450 BSC						
k1	0.225 BSC						
Z	0.20						
All Dimensions in mm							

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.650
G	0.125
G1	0.350
X	0.400
X1	1.700
Υ	0.365
Y1	0.515
Y2	0.825
Y3	2.330



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